

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10598469			
<b>Filing Date:</b>				
<b>Title of Invention:</b>	Multilayer Substrate Manufacturing Method			
<b>First Named Inventor/Applicant Name:</b>	Takeshi Nakamura			
<b>Filer:</b>	Samuel Borodach/Gina Maldonado			
<b>Attorney Docket Number:</b>	14225-112US1 F1040898US00			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
Late filing fee for oath or declaration	1051	1	130	130
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130